



NOW! 300mm WAFER DICING



CORWIL is the leader in wafer backgrinding, wafer dicing and visual inspection to commercial, military and medical specs. CORWIL's newest addition in dicing equipment is a fully automatic, latest state-of-the-art 12 inch dicing saw that strengthens CORWIL's technical leadership for chip-free and fast turn-around dicing. CORWIL dices Si, GaAs, Sapphire, SiGe, laminates and many other materials and CORWIL is unsurpassed in IC assembly in ceramic, BGA, flip-chip, and MLF/QFN type packages.

- **High Volume — Millions of dice per month**
- **Automatic High-Speed Pick-and-Place**
- **Automatic Vision Inspection Systems**
- **Low K, MEMS and Optical/Imaging wafers processed**
- **Experts in Multi-die Type Wafer dicing**
- **Highest Quality and Best Service in the Industry**

*Since 1990 CORWIL has built its reputation providing customers with:
Excellent Quality and Superior Service*

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ISO 9001:2000 Registered

DSCC QML Certification

MIL-PRF-38535

MIL-STD-883